

**Key**

- Front Soft Gold
- Front Tracking
- Main Central PCB
- Rear Tracking
- Rear Soft Gold

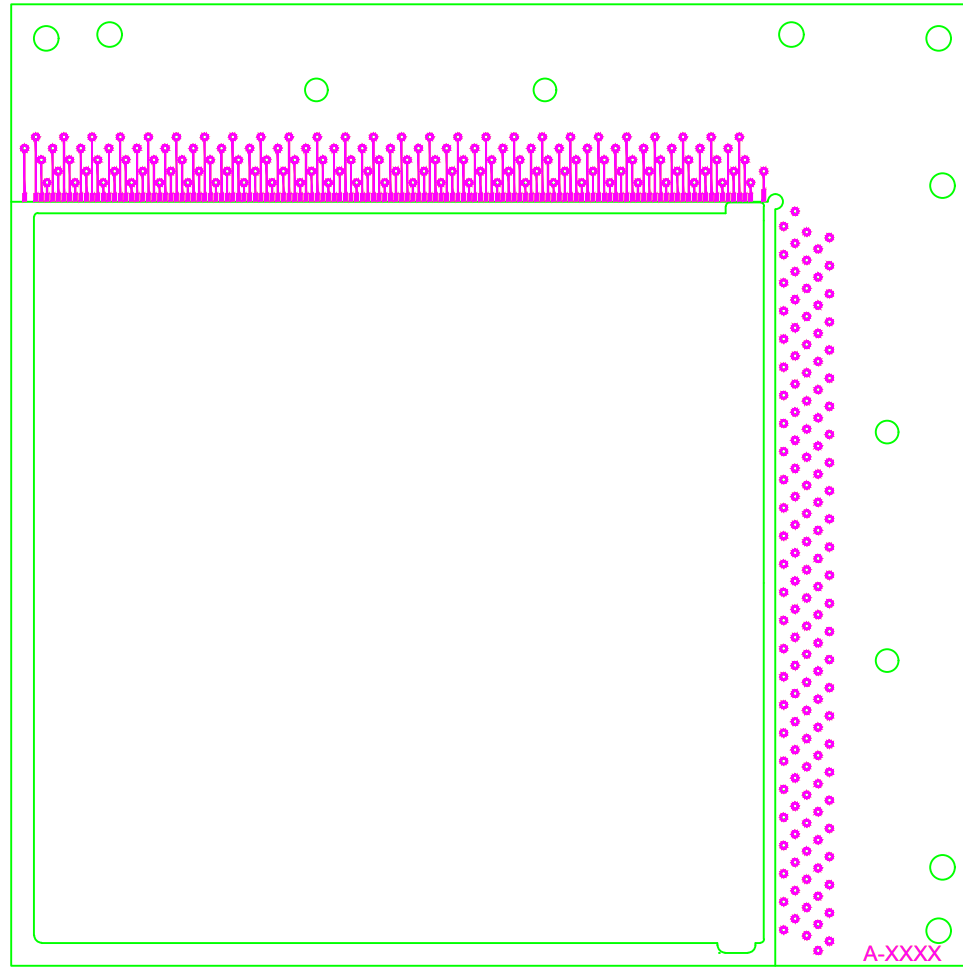
Drawn. <b>N.W</b>	Checked <b>S.W</b>	Date 14/06/2021	Tolerances Unless Stated		Material - 2.4 mm Thick Rogers PCB material
			x.xx ± 0.1mm	Plating - 1 ounce Copper with Soft Gold Pads	
Design Approved			x.xxx ± 0.01mm	Solder Resist Front - No	Front Spacer - N/A
			Angular ± 0.25°	Solder Resist Rear - No	Rear Spacer - N/A
			Material Thickness ± 10%	Ledge - 1.0 mm deep from top	

Title. **TTT14 PCB Rev 9**  
**All layers**

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Scale: **1:1**    Dims In. **mm**    Drg. No. **C-3517**



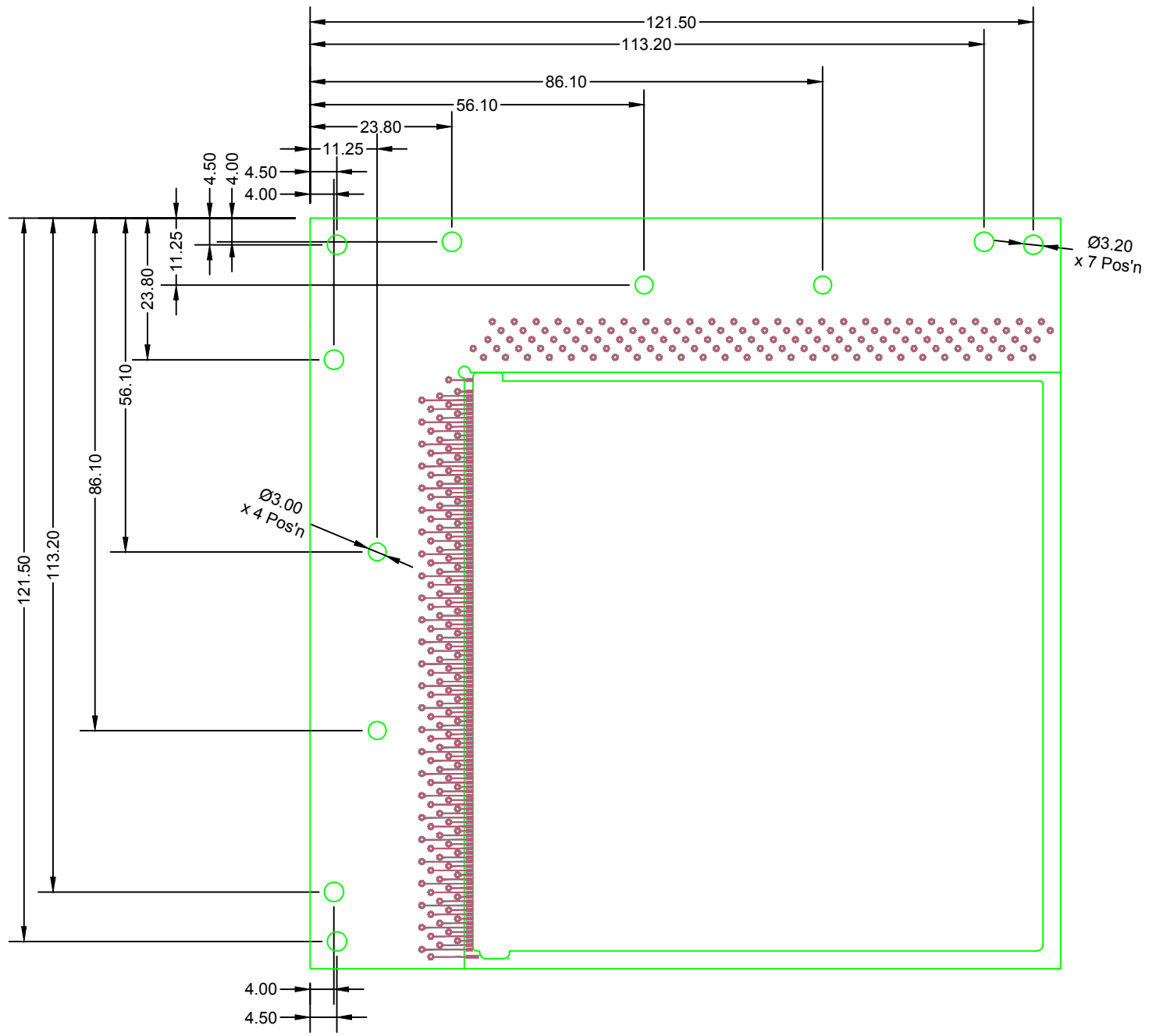
Drawn. <b>N.W</b>	Checked <b>S.W</b>	Date 14/06/2021	Tolerances Unless Stated		Material - 2.4 mm Thick Rogers PCB material
Design Approved			x.xx ± 0.1mm	Plating - 1 ounce Copper with Soft Gold Pads	
			x.xxx ± 0.01mm	Solder Resist Front - No	Front Spacer - N/A
			Angular ± 0.25°	Solder Resist Rear - No	Rear Spacer - N/A
			Material Thickness ± 10%	Ledge - 1.0 mm deep from top	

Title.  
**TTT14 PCB Rev 9**  
**No Solder Resist**  
**Front View**

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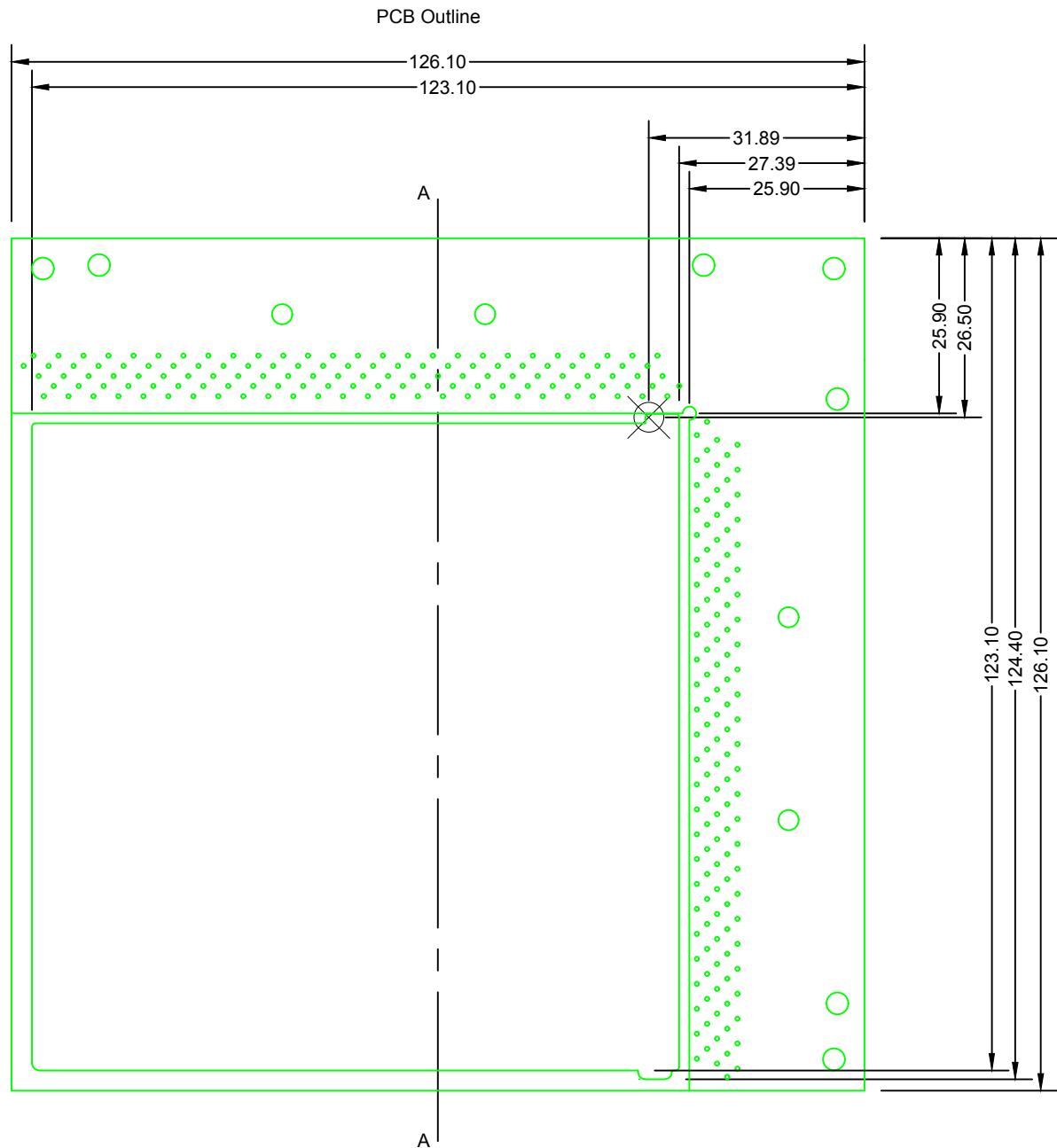
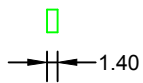
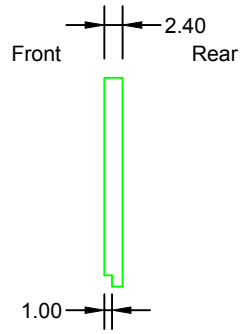
Drawn. N.W	Checked S.W	Date 14/06/2021	Tolerances Unless Stated	Material - 2.4 mm Thick Rogers PCB material
Design Approved			x.xx ± 0.1mm	Plating - 1 ounce Copper with Soft Gold Pads
			x.xxx ± 0.01mm	Solder Resist Front - No Front Spacer - N/A
			Angular ± 0.25°	Solder Resist Rear - No Rear Spacer - N/A
			Material Thickness ± 10%	Ledge - 1.0 mm deep from top

Title: TTT14 PCB Rev 9  
 No Solder Resist  
 Rear View And Mounting Hole Details

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Scale: 1:1 | Dims In. mm | Drg. No. C-3517

Side Profile

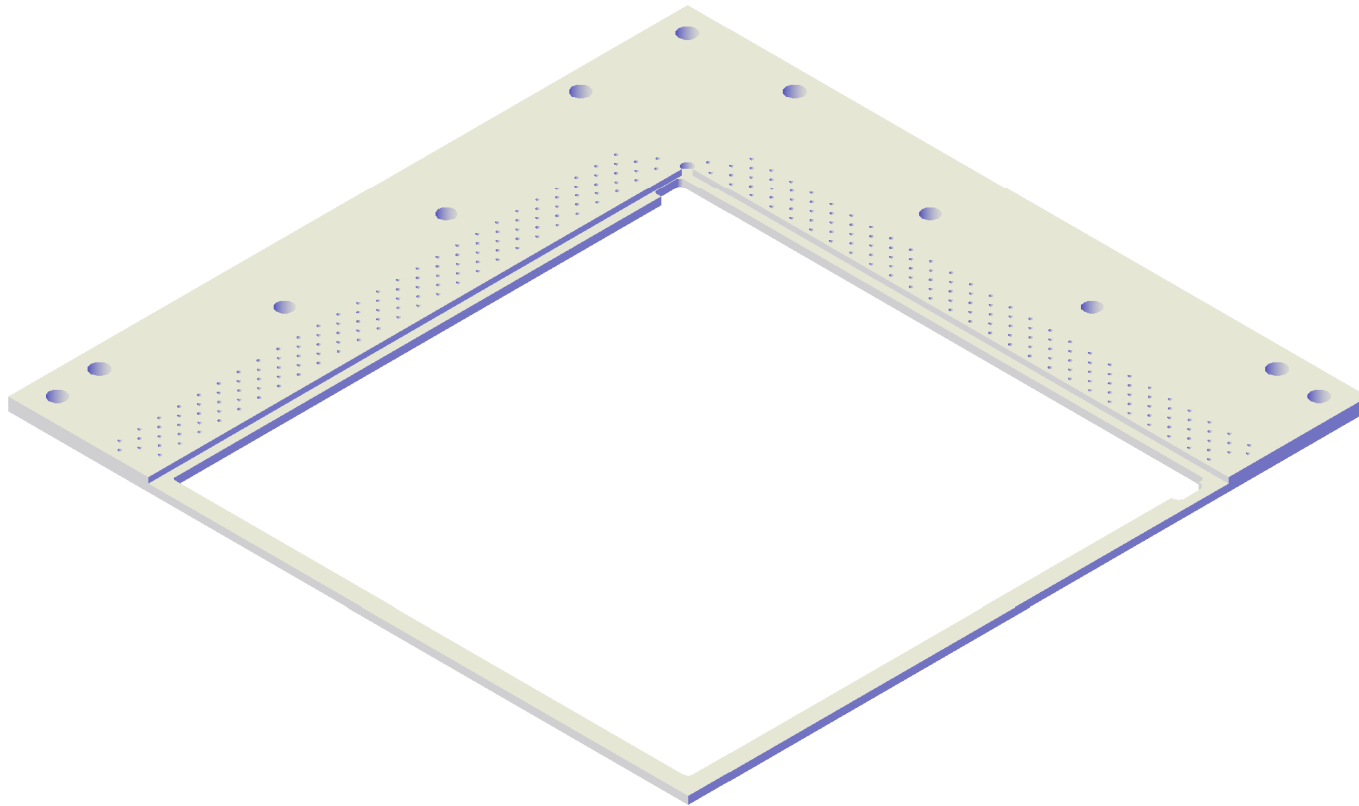


Drawn. <b>N.W</b>	Checked <b>S.W</b>	Date <b>14/06/2021</b>	Tolerances Unless Stated	Material - 2.4 mm Thick Rogers PCB material	Title. <b>TTT14 PCB Rev 9 No Solder Resist Outline View</b>
Design Approved			x.xx ± 0.1mm	Plating - 1 ounce Copper with Soft Gold Pads	
			x.xxx ± 0.01mm	Solder Resist Front - No Front Spacer - N/A	
			Angular ± 0.25°	Solder Resist Rear - No Rear Spacer - N/A	
			Material Thickness ± 10%	Ledge - 1.0 mm deep from top	

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Scale: **1:1** | Dims In. **mm** | Drg. No. **C-3517**



Drawn.	Checked	Date	Tolerances Unless Stated		Material - 2.4 mm Thick Rogers PCB material	
N.W	S.W		x.xx ± 0.1mm	Plating - 1 ounce Copper with Soft Gold Pads		
Design			x.xxx ± 0.01mm	Solder Resist Front - No	Front Spacer - N/A	
Approved			Angular ± 0.25°	Solder Resist Rear - No	Rear Spacer - N/A	
			Material Thickness ± 10%	Ledge - 1.0 mm deep from top		

Title. **TTT14 PCB Rev 9**  
**No Solder Resist**  
**3D View**

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